

■Features

- Single chip
- Super high brightness of surface mount LED
- Sorting for Iv and Vf @ 5mA of If
- Compact package outline (LxWxT) of 1.6mm x 0.8mm x 0.6mm
- Compatible to IR reflow soldering.

■Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

■Absolute Maximum Rating

(Ta=25°C)

Item	Symbol	Value		Unit
		M/W/K4/VX/B5/B6/G4/G5	G8/Y5/O5/R5	
DC Forward Current	I _F	20	20	mA
Pulse Forward Current#	I _{FP}	100	100	mA
Reverse Voltage	V _R	5	5	V
Power Dissipation	P _D	68	48	mW
Operating Temperature	Topr	-40 ~ +85		°C
Storage Temperature	T _{Stg}	-40~+85		°C
Lead Soldering Temperature	T _{Sol}	260°C/10sec		-

#Pulse width Max 0.1ms, Duty ratio max 1/10

■Electrical -Optical Characteristics

(Ta=25°C)

Part Number	Color	V _F (V)			I _R (μA)	Iv(mcd)			λD(nm)			201/2(deg)
		Min.	Typ.	Max.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Typ.
		I _F =5mA			V _R =5V	I _F =5mA						
OSM20603C1E	Candle Warm White	M2		2.5	2.8	3.4	10	60	-	160	2000-2500K(X:0.51, Y:0.41)	120
OSM50603C1E	Warm White	M5		2.5	2.8	3.4	10	60	-	160	2700-3300K(X:0.44, Y:0.41)	120
OSM70603C1E	Neutral White	M7		2.5	2.8	3.4	10	250	-	350	4000-5000K(X:0.37, Y:0.38)	120
OSW40603C1E	Pure White	W4		2.5	2.8	3.4	10	100	-	200	5500-8500K(X:0.31, Y:0.33)	120
OSW50603C1E	Cool White	W5		2.5	2.8	3.4	10	100	-	200	8500-18000K(X:0.27, Y:0.28)	120
OSK40603C1E	Pink	K4		2.5	2.8	3.4	10	50	-	100	X=0.31, Y=0.20	120
OSVX0603C1E	Violet	VX		2.5	2.8	3.4	10	70	-	130	X=0.20, Y=0.09	120
OSB50603C1E	Blue	B5		2.5	2.8	3.4	10	14	-	40	455 470 475	120
OSB60603C1E	Ice Blue	B6		2.5	2.8	3.4	10	80	-	200	X=0.18 Y=0.26	120
OSG40603C1E	Emerald Green	G4		2.5	2.8	3.4	10	120	-	220	510 515 520	120
OSG50603C1E	True Green	G5		2.5	2.8	3.4	10	120	-	220	520 525 530	120
OSG80603C1E	Yellow Green	G8		1.6	1.8	2.4	10	5	-	15	565 570 575	120
OSY50603C1E	Yellow	Y5		1.6	1.8	2.4	10	15	-	50	585 590 595	120
OSO50603C1E	Orange	O5		1.6	1.8	2.4	10	15	-	50	600 605 610	120
OSR50603C1E	Red	R5		1.6	1.8	2.4	10	15	-	50	617 625 630	120

*1 Tolerance of measurements of chromaticity coordinate is $\pm 10\%$

*2 Tolerance of measurements of dominant wavelength is $\pm 1\text{nm}$

*3 Tolerance of measurements of luminous intensity is $\pm 15\%$

*4 Tolerance of measurements of forward voltage is $\pm 0.1\text{V}$

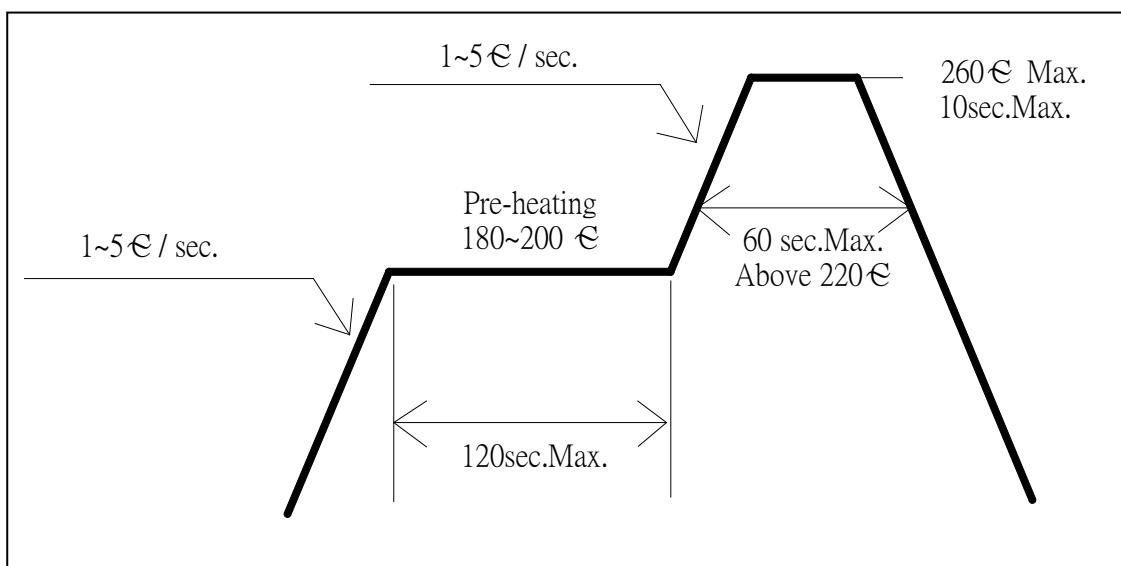
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■ **Soldering Conditions**

Reflow Soldering		Hand Soldering	
Pre-Heat	180 ~ 200°C	Temperature Soldering time	350°C Max. 3 sec. Max. (one time only)
Pre-Heat Time	120 sec. Max.		
Peak Temperature	260°C Max.		
Dipping Time	10 sec. Max.		
Condition	Refer to Temperature-profile		

• **Reflow Soldering Condition(Lead-free Solder)**



*Recommended soldering conditions vary according to the type of LED

*Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.

*A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.

• All SMD LED products are pb-free soldering available.

• Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.

• Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

• Reflow soldering should not be done more than two times.

• When soldering, do not put stress on the LEDs during heating.

• After soldering, do not warp the circuit board.



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Light It Up

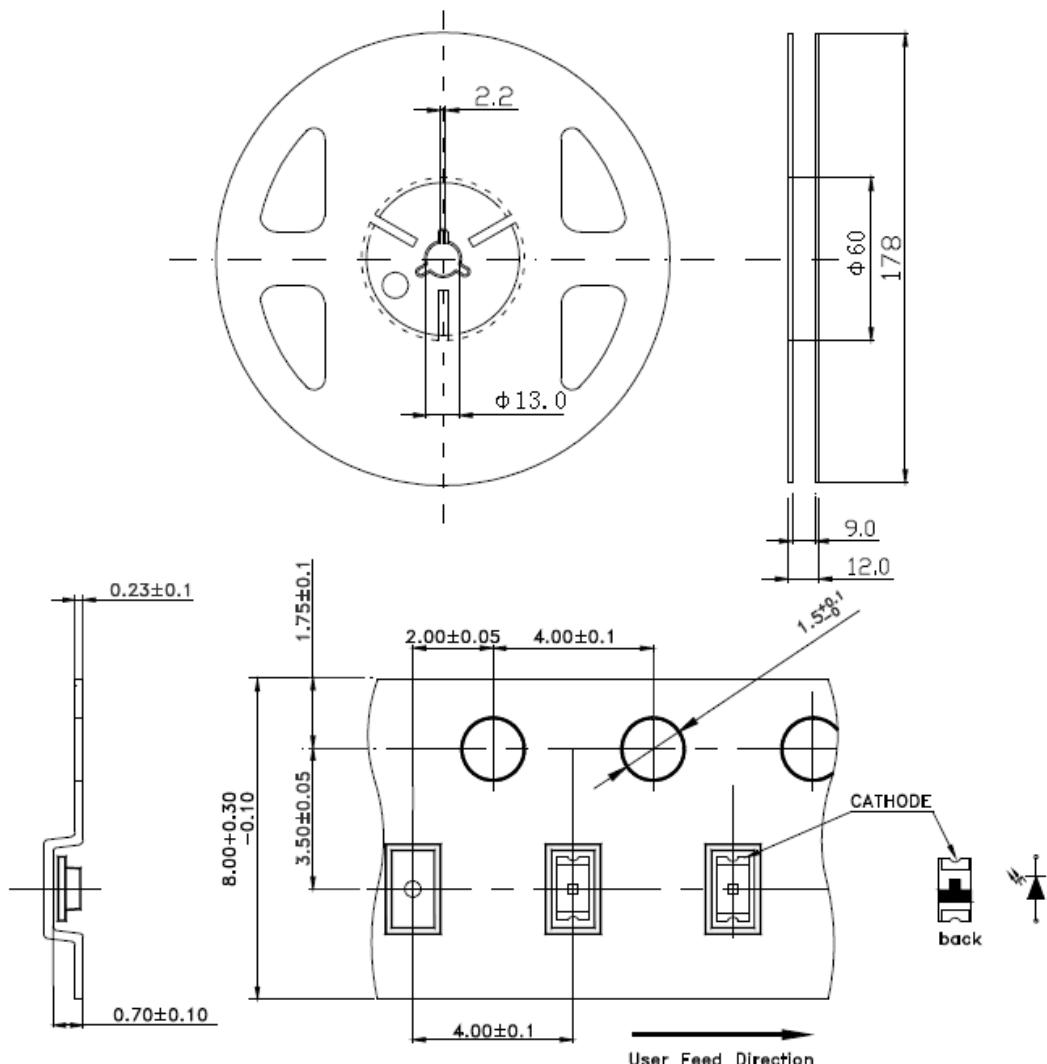
1.6 x 0.8 x 0.6 mm Chip LED

OSXX0603C1E

■ Reel & Tape Dimensions

Quantity: 4,000 units/reel

Diameter: 178 mm

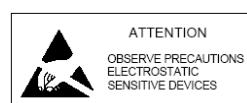


Notes: 1. All dimensions are in millimeters ;

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REACH
The new EU chemicals legislation



■ Cautions:

1. After open the package, the LED's floor life is 4 Weeks under 30°C or less and 60%RH or less(MSL:2a).
2. Heat generation must be taken into design consideration when using the LED.
3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.

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